

JEDEC MANUAL

JEDEC COMMITTEE SCOPE MANUAL

JM18T (Revision of JM18S, April 2018)

JUNE 2022

JEDEC SOLID STATE TECHNOLOGY ASSOCIATION



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JEDEC COMMITTEE SCOPE MANUAL

(From JCB-96-73, JCB-98-94, JCB-98-97, JCB-98-102, JCB-98-105, JCB-98-107, JCB-99-03, JCB-00-19, JCB-00-60, JCB-01-61, JCB-01-86, JCB-02-137, JCB-04-65, JCB-04-91, JCB-05-130, JCB-05-132, JCB-06-31, JCB-06-58, JCB-07-26A, JCB-07-54, JCB-07-55, JCB-07-63, JCB-07-71, JCB-07-75, JCB-08-06, JCB-08-08, JCB-08-15, JCB-08-31, JCB-08-38, JCB-08-64, JCB-08-89, JCB-08-90, JCB-10-87, JCB-11-69, JCB-11-70, JCB-11-83, JCB-12-28, JCB-12-30, JCB-14-42, JCB-15-07, JCB-15-50, JCB-17-26, JCB-18-17, JCB-21-19, JCB-21-45, and JCB-22-04 formulated by the JEDEC Solid State Technology Association.)

1 Introduction

JEDEC is an independent incorporated Association governed by a Board of Directors (Board). The Association facilitates standardization within the solid-state, microelectronics, and associated industries, and other related activities through special purpose committees.

The Association and its members are committed to foster open competition in the development of products and services.

The scope of JEDEC includes but is not necessarily limited to areas relating to (1) solid state devices, (2) integrated circuits, (3) electronic modules and associated electronic components, and (4) various manufacturing functions/processes.

The governing body of JEDEC is the JEDEC Board of Directors which is comprised of individual Directors (or their alternates) representing JEDEC member companies. The JEDEC Board of Directors is responsible for establishing appropriate committees to conduct its standardization activities. These committees are assigned either service or product responsibilities.

Service committees address a specific subject that may impact several product types. Activities include package outlines, terms and definitions, government standards, and international standards. Service committees establish liaison with other JEDEC committees and with agencies outside JEDEC. For service committees, the first digit of the two-digit committee designator is the number 1.

Product committees address a specific type product. Examples include test methods, device specification format and minimum content, pinouts, interface requirements, and applications. Product committees establish liaison with other JEDEC committees and with agencies outside JEDEC. For product committees, the first digit of the two-digit committee designator is the number 2 or higher.

It is a primary function of each committee to propose JEDEC Standards and to formulate policies, procedures, formats, and other documents that are then submitted to the Board of Directors for action or approval. This publication identifies the service and product committees established by the Board of Directors and defines their scopes.

For more information about JEDEC policies, refer to JM21: JEDEC Manual of Organization and Procedure.

2 Service committees

JC-11 Committee: Mechanical Standardization

Activities within JC-11's scope cover all aspects of the mechanical design, integration, interoperability and standardization of all devices covered within JEDEC. These activities include generating design guidelines, standardized measuring methods for mechanical features, and standard- or registration-type mechanical outlines for microelectronic packages and assemblies, corresponding socket outlines, mechanical, environmental and ergonomic performance specifications, footprints and land patterns, and development of designators for semiconductor device packages. To accomplish these functions, the committee provides technical support and design recommendations to establish and define parameters that ensure mechanical interchangeability of parts. In addition, JC-11's includes standardization of the mechanical definition of all electronic, electrical, and hardware components to enable process efficiencies throughout the electronic design and manufacturing process and includes but is not limited to the standardization of 3D models. JC-11 is further responsible for a parametric XML format to communicate all electronic, electrical, and hardware part model characteristics to enable these efficiencies.

Other items, such as the materials, surface finish, and temper, that may affect the form, fit, function, and/or reliability of the interfaces of the product are also included. These parts are limited to the following: discrete, monolithic, multichip, and hybrid circuits; microcircuit modules; intermediate package carriers and containers; uncased devices; and certain package-related assembly or fabrication items. The committee maintains liaison with other JEDEC committees and outside organizations engaged in activities related to similar mechanical standardization work.

- **JC-11.1 Subcommittee: Editorial Practices and Procedures**

Reviews, corrects, and gives editorial approval for distribution and publication of ballots and outlines.

- **JC-11.2 Subcommittee: Design Requirements**

Establish guidelines and methods for obtaining the desired dimensions and tolerancing for various classes of packages and related items, (JEDEC Standard No. 95-1, *Design Handbook*.), and develops designators for semiconductor-device packages, (JEDEC Standard No. 30, Descriptive Designation System for Semiconductor-Device Packages.)

- **JC-11.4 Subcommittee: Uncased Devices**

Prepare mechanical outlines for uncased devices including, but not limited to, the following configurations: uncased discrete or integrated circuits, flip chip, beam lead, and tape mounted, and chip scale in general.

- **JC-11.5 Subcommittee: Package Interface (Inactive)**

Prepares mechanical outlines for device test and transport mediums such as test carriers, matrix trays and shipping tubes, test sockets, and contactors.

2 Service committees (cont'd)

JC-11 Committee: Mechanical (Package Outlines) Standardization (cont'd)

- **JC-11.7 Subcommittee: IEC Interface**

Coordinates with the International Electrotechnical Commission (IEC) Subcommittee 47D on work affecting mechanical outlines.

Reference information only:

IEC SC47D: Mechanical standardization of semiconductor devices

- ***WG-1 — Package outlines***

Tasks include the generation of outline drawings to ensure mechanical interchangeability, automatic handling, and mounting.

- ***WG-2 — Terms, definitions, practices, and procedures***

Tasks include the generation, coordination, and review of terms, definitions, and symbols. In addition, the working group establishes drawing formats and methods of dimensioning and tolerancing.

- **JC-11.10 Subcommittee: Microelectronic Ceramic Packages**

Prepare mechanical outlines for ceramic packages.

- **JC-11.11 Subcommittee: Microelectronic Plastic Packages**

Prepare mechanical outlines for plastic packages.

- **JC-11.13 Subcommittee: Gauges and Tools for Semiconductor Packages and Related Parts (Inactive)**

Specifies mechanical measuring methods, mechanical gauges, fixtures, and overlays that are recommended for use in verifying the dimensions of uncased devices, semiconductor packages, and package interface media.

- **JC-11.14 Subcommittee: Microelectronic Assemblies**

Prepare mechanical outlines for assemblies of microelectronic packages.

2 Service committees (cont'd)

JC-13 Committee: Government Liaison

JC-13 Committee is responsible for standardizing quality and reliability methodologies for solid state products used in military, space, and other environments requiring special-use condition capabilities beyond standard commercial practices. This includes long-term reliability and/or special screening requirements.

Implementation:

The purpose of the JC-13 Committee is to provide the member companies and their customers with uniform, cost-effective, proven, customer-accepted methodologies for specifying and evaluating special-use products, with the end goal of enhancing the performance and reliability of those products. Activities within the JC-13 Committee include the development, coordination, and maintenance of standards documents regarding product quality and reliability, validation systems, and process management. The committee also contributes to similar and related documents that are generated and maintained by other organizations. To accomplish this charter, the committee maintains liaisons with customers, other JEDEC committees, government agencies, and interested parties that have special application needs.

- **JC-13.1 Subcommittee: Discrete Devices**

Provide technical support and recommendations to the Department of Defense (DoD) concerning environmental and electrical test methods and procedures for discrete solid state electronic components. This subcommittee also develops quality assurance programs and methods.

- **JC-13.2 Subcommittee: Microelectronic Devices**

Provide technical support and recommendations to the U.S. Government and Space agencies concerning electrical, environmental, and quality and reliability assurance test methods for microelectronic devices. Members of the subcommittee contribute technical expertise in quality control and reliability engineering, environmental and simulated lifetesting, and electronic design and wafer fabrication, assembly, testing techniques.

- **JC-13.4 Subcommittee: Radiation Hardness: Assurance and Characterization**

Maintain liaison between component manufacturers, users, and government agencies on all issues related to the radiation hardness assurance and characterization of solid state devices. All considerations of specifications, standards, methods of testing, and other technical issues related to the behavior of solid state devices in a radiation environment are within the scope of this subcommittee. The subcommittee promotes uniform standards, methods, and specifications acceptable to manufacturers, users, and government agencies through the solicitation of technical help and advice from appropriate experts. The subcommittee provides a forum where manufacturers' capabilities can be discussed.